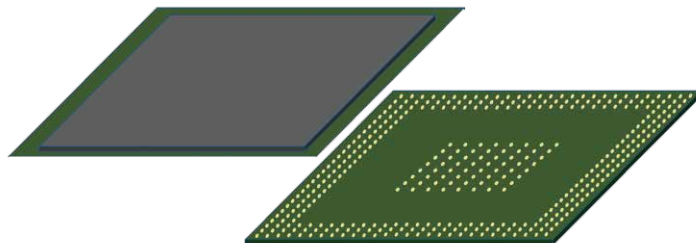


# FCBGA

## Flip Chip-Ball Grid Array

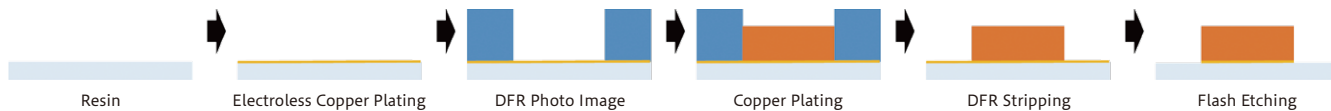
### 用途 Application

- CPU基板  
CPU PCB
- ASIC  
Application Specific Integrated Circuit



### 工法 Construction method

SAP  
Semi Additive Process

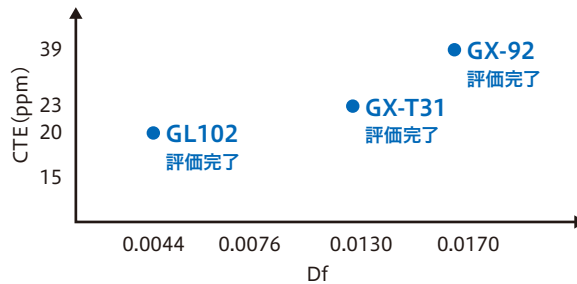


### 特長 Features

高精細パターン形成  
High definition pattern formation

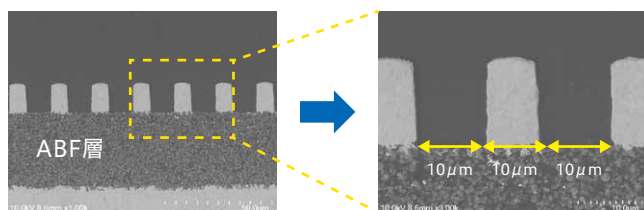
### 適用材料 Materials

ABF材 ABF material



### パターン形成 Pattern formation

ABF layer  
Target L/S = 10/10 $\mu$ m



### 構造事例 (断面図) Constructional Example (Cross Section)

